

10/567,253

cls. 1 & 4

Application No.: NEW

Docket No.: 3273-0218PUS1

ODP

cls. 6-15

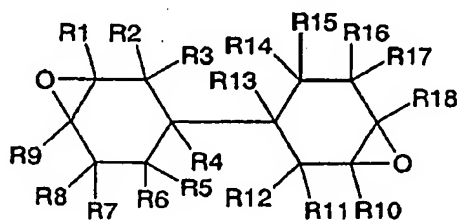
AMENDMENTS TO THE CLAIMS

1. (Original) A thermosetting resin composition comprising 100 parts by weight of an epoxy composition (E) and 0.01 to 20 parts by weight of a cationic polymerization initiator (C), the epoxy composition (E) comprising 10 to 99 percent by weight of an ester-free alicyclic epoxy compound (A) having two alicyclic epoxy groups and no ester bond per molecule; and 90 to 1 percent by weight of another epoxy compound (B) differing from the epoxy compound (A), the total of (A) and (B) being 100 percent by weight.

2. (Original) The thermosetting resin composition of claim 1, further comprising 50 parts by weight or less of an epoxy-containing acrylic resin (D) differing from the components (A) and (B), to 100 parts by weight of the epoxy composition (E).

3. (Original) The thermosetting resin composition of claim 2, wherein the epoxy-containing acrylic resin (D) further comprises hydroxyl group in addition to epoxy group.

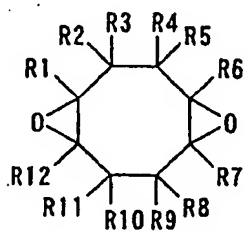
4. (Original) The thermosetting resin composition of any one of claims 1 to 3, wherein the ester-free alicyclic epoxy compound (A) is an epoxy compound represented by Structural Formula (1):



(1)

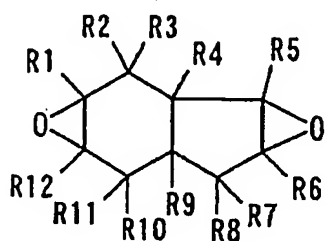
wherein R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, and R18 may be the same as or different from one another and are each hydrogen atom, a halogen atom, a hydrocarbon group which may comprise oxygen atom or a halogen atom, or a substituted or unsubstituted alkoxy group.

5. (Original) The thermosetting resin composition of any one of claims 1 to 3, wherein the ester-free alicyclic epoxy compound (A) is an epoxy compound represented by Structural Formula (3):



wherein R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, and R12 may be the same as or different from one another and are each hydrogen atom, a halogen atom, a hydrocarbon group which may comprise oxygen atom or a halogen atom, or a substituted or unsubstituted alkoxy group.

6. (Original) The thermosetting resin composition of any one of claims 1 to 3, wherein the ester-free alicyclic epoxy compound (A) is an epoxy compound represented by Structural Formula (5):



(5)

wherein R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, and R12 may be the same as or different from one another and are each hydrogen atom, a halogen atom, a hydrocarbon group which may comprise oxygen atom or a halogen atom, or a substituted or unsubstituted alkoxy group.

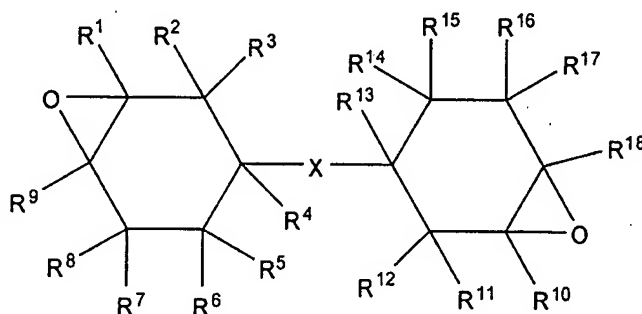
7. (Currently amended) An optically transparent material prepared by thermally curing the thermosetting resin composition of ~~any one of claims 1 to 6~~ claim 1.

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Currently amended) A liquid epoxy resin composition comprising an epoxy resin, and a curing agent and/or a curing accelerator, wherein the epoxy resin comprises, in an amount of 100 to 3029% by weight, an alicyclic compound $[[A]]$ represented by the following formula (I):



(I)

(wherein X represents a divalent group selected from the group consisting of oxygen atom, sulfur atom, $-\text{SO}-$, $-\text{SO}_2-$, $-\text{CH}_2-$, $-\text{C}(\text{CH}_3)_2-$, $-\text{CBr}_2-$,

$\text{—C(CBr}_3)_2\text{—}$, $\text{—C(CF}_3)_2\text{—}$, $\text{—C(CCl}_3)_2\text{—}$ and $\text{—CH(C}_6\text{H}_5)\text{—}$, [[or]]and a single bond linking two alicyclic rings; and R^1 to R^{18} ~~are the same or different and each represents one~~ independently selected from the group consisting of hydrogen atom, halogen atom, a hydrocarbon group which may contain oxygen atom or halogen atom, and an alkoxyl group ~~which may have substituent groups~~.

6. (Currently amended) The epoxy resin composition according to claim 5, wherein the alicyclic epoxy compound $[[\text{(A)}]]$ represented by the formula (I) is an epoxy compound produced by using percarboxylic acid having water content of 2% by weight or less.
7. (Withdrawn) The liquid epoxy resin composition according to claim 5, wherein the curing agent is an initiator which releases a substance initiating cationic polymerization by heating.
8. (Original) The liquid epoxy resin composition according to claim 5, wherein the curing agent is a liquid acid anhydride.
9. (Cancelled)
10. (Original) The liquid epoxy resin composition as claimed in claim 5, which is used for photosemiconductor encapsulation.
- 11-17. (Cancelled)

18. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is a compound having a function of promoting a curing reaction when the epoxy resin is hardened by an acid anhydride.
19. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is a diazabicycloundecene-based accelerator.
20. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is present in an amount of 0.3 to 10 parts by weight based on 100 parts by weight of the epoxy resin.
21. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is present in an amount of 1 to 10 parts by weight based on 100 parts by weight of the epoxy resin.
22. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is present in an amount of 1 to 5 parts by weight based on 100 parts by weight of the epoxy resin.
23. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is 1,8-diazabicyclo[5.4.0]undecene-7, or a salt thereof.
24. (new) The liquid epoxy resin composition according to claim 5, wherein said curing accelerator is selected from the group consisting of a tertiary amine, an imidazole, an organic phosphine compounds, a tertiary amine salt, a phosphonium salt, or a metal salt.